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**CONNECTION BETWEEN SEMICONDUCTOR  
UNIT AND DEVICE CARRIER**

**ABSTRACT OF THE DISCLOSURE**

5           The present invention provides methods / interconnection portions for  
connecting at least a semiconductor unit such as chip to at least a device carrier (such as  
lead frame) lacking good mechanism for limiting solder flowing of melted metal. The  
methods are characterized by forming at least a device carrier bump jutting out from a  
metal surface of the device carrier lacking good mechanism thereon for limiting solder  
10   flowing of melted metal, and forming at least a chip bump which melts for the device  
carrier bump to approach the electrode of the chip and have an end on the electrode of  
the chip. The chip bump melts to surround and adhere to the device carrier bump, and  
to have one end on the metal surface of the device carrier, resulting in an  
interconnection portion including a first part and a second part both having one end on  
15   the metal surface and another end on the chip.